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Title:

GRADED Ge_xSe_{100-x} CONCENTRATION IN PCRAM

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GRADED $\text{Ge}_x\text{Se}_{100-x}$ CONCENTRATION IN PCRAM

BACKGROUND OF THE INVENTION

FIELD OF THE INVENTION

[0001] The invention relates to the field of random access memory (RAM) devices formed using chalcogenide glass layers, and in particular to an improved programmable conductor random access memory (PCRAM) element design utilizing germanium-selenide glass layers.

DESCRIPTION OF THE RELATED ART

[0002] Programmable conductor memory elements recently have been investigated for suitability as semi-volatile and non-volatile random access memory devices. One known PCRAM element composition utilizes a germanium-selenide chalcogenide glass of $\text{Ge}_x\text{Se}_{100-x}$ stoichiometry. A metal, such as silver, is incorporated into the germanium-selenide glass. It is believed that the metal provides conductivity to the element thus allowing the element to be switched between two resistance states. Particularly, a silver-containing $\text{Ge}_x\text{Se}_{100-x}$ glass layer is positioned between two electrodes utilized in a PCRAM element.

[0003] The resistance of the silver-containing germanium-selenide glass layer can be changed between high resistance and low resistance states. The programmable conductor memory element is normally in a high resistance state when at rest. A write operation to a low resistance state is performed by applying a voltage potential across the two electrodes. When set in a low resistance state, the state of the memory element

will remain intact for days or weeks after the voltage potentials are removed. The memory element can be returned to its high resistance state by applying a reverse voltage potential between the electrodes as used to write the element to the low resistance state. Again, the highly resistant state is maintained once the voltage potential is removed. This way, such a device can function, for example, as a resistance variable memory element having two resistance states, which can represent two logic states.

[0004] The stoichiometry of a $\text{Ge}_x\text{Se}_{100-x}$ glass inherently provides many different glass compositions depending on the value of x. Certain structural characteristics of $\text{Ge}_x\text{Se}_{100-x}$ have been observed with a change in the value of x. Specifically, referring now to prior art FIG. 1 (adapted from Boolchand, P., et al. "Onset of Rigidity in Steps in Chalcogenide Glasses – The Intermediate Phase" in M. Thorpe (ed.) Properties and Applications of Amorphous Materials, NATO Science Series (Plenum/Kluwer, 2001)), $\text{Ge}_x\text{Se}_{100-x}$ glasses that are selenium-rich, i.e., glasses having a stoichiometry whereby x is less than or equal to 20, have a loose or open glass matrix as a result of the higher proportion of Se-Se bonds which occur when the relative number of germanium atoms is low. By contrast, $\text{Ge}_x\text{Se}_{100-x}$ glass with values of x greater than 26 have a tight or rigid glass matrix due to the greater proportion of Ge-Se bonds present in the glass. $\text{Ge}_x\text{Se}_{100-x}$ glass with values of x between 20 and 26 has an intermediate glass matrix. Rigidity is relative and based on the stoichiometry of the $\text{Ge}_x\text{Se}_{100-x}$ glass. Accordingly, a $\text{Ge}_{40}\text{Se}_{60}$ glass is more rigid than a $\text{Ge}_{33}\text{Se}_{67}$ glass, and $\text{Ge}_{25}\text{Se}_{75}$ glass is more rigid than $\text{Ge}_{20}\text{Se}_{80}$ glass. Glass matrix structure is also relative and a function of the value of x.

Therefore, a $\text{Ge}_{40}\text{Se}_{60}$ glass has a tighter glass matrix structure than a $\text{Ge}_{33}\text{Se}_{67}$ glass, and $\text{Ge}_{25}\text{Se}_{75}$ glass has a tighter glass matrix structure than $\text{Ge}_{20}\text{Se}_{80}$ glass.

[0005] The structure of the glass matrix, i.e., tight versus open, affects the switching characteristics of the memory element. If the $\text{Ge}_x\text{Se}_{100-x}$ glass has a tight matrix, then a larger resistance change is inhibited when a memory element switches from an on to an off state. On the other hand, if the germanium-selenide glass matrix is looser, or more open, then a larger resistance change is more easily facilitated. Accordingly, since glasses having a tight matrix inhibit a large resistance change, a PCRAM element utilizing a glass with a tight matrix will keep the programmed state longer than a PCRAM element utilizing a glass with an open matrix.

[0006] While a PCRAM element comprised exclusively of a glass with an open matrix will be placed in a low resistance state or a high resistance state more quickly than a PCRAM element comprised exclusively of a glass with a tight matrix, glass with an open matrix used by itself is also not ideal. First, a PCRAM element utilizing glass with an open matrix may allow multiple low resistive pathways to be formed during programming. The tighter glass matrix will allow formation of a preferred conductive pathway with the properties of improved switching reliability and reduced resistance drift because there are fewer resistively decaying conductive pathways. Furthermore, the low melting point of selenium-rich glass, i.e., glass with an open matrix makes fabrication of PCRAM elements containing only glass with an open matrix difficult and complicated.

[0007] What is needed is a design for a PCRAM element which provides faster operation and better data retention than that which can be obtained with either open-matrix or tight-matrix glass.

SUMMARY

[0008] The present invention provides a new structure for a PCRAM element which utilizes Ge_xSe_{100-x} glass layers of varying stoichiometry. The present invention additionally provides a method for making a PCRAM element comprising Ge_xSe_{100-x} glass layers of varying stoichiometry. In the preferred embodiment, the PCRAM element structure comprises a first electrode positioned beneath a first germanium-selenide glass layer with a stoichiometry providing a certain glass matrix structure. Located above this first germanium-selenide glass layer is a second germanium-selenide glass layer with a different stoichiometry providing a different glass matrix structure than the stoichiometry of the first germanium-selenide glass layer provides. A metal is introduced into each of these germanium-selenide glass layers. A second electrode is disposed on top of the second germanium-selenide glass layer.

[0009] The preferred embodiment of the method of fabricating the present invention includes: forming an insulating layer over a first electrode; forming an opening in the insulating layer to expose a portion of the first electrode; forming a first germanium-selenide glass layer of a specific stoichiometry in the opening; introducing a metal into the first germanium-selenide glass layer; forming a second germanium-selenide glass layer of a stoichiometry different from that of the first germanium-selenide glass layer, and hence a different glass structure; introducing a metal into the

second germanium-selenide glass layer; and forming a second electrode over the insulating layer and over the second metal-containing germanium-selenide glass layer.

[0010] Additional advantages and features of the present invention will be apparent from the following detailed description provided in connection with the accompanying drawings which illustrate exemplary embodiments of the invention.

BRIEF DESCRIPTION OF THE DRAWINGS

[0011] FIG. 1 shows the values of x in the formula Ge_xSe_{100-x} which provide for an open matrix ("floppy") and a tight matrix ("rigid");

[0012] FIG. 2 is a flowchart showing the steps of fabricating a memory element in accordance with the preferred embodiment of the present invention;

[0013] FIG. 3 is a cross-sectional view of a semiconductor substrate having a first insulating layer, a bottom electrode and second insulating layer;

[0014] FIG. 4 shows the substrate of FIG. 3 undergoing the process of the preferred embodiment of the present invention;

[0015] FIG. 5 shows the substrate of FIG. 4 at a processing step subsequent to that shown in FIG. 4;

[0016] FIG. 6 shows the substrate of FIG. 5 at a processing step subsequent to that shown in FIG. 5;

[0017] FIG. 6A shows the substrate of FIG. 5 at an alternative processing step subsequent to that shown in FIG. 5;

[0018] FIG. 7 shows the substrate of FIG. 6 at a processing step subsequent to that shown in FIG. 6;

[0019] FIG. 7A shows the substrate of FIG. 6A at a processing step subsequent to that shown in FIG. 6A;

[0020] FIG. 8 shows the substrate of FIG. 7 at a processing step subsequent to that shown in FIG. 7;

[0021] FIG. 9 shows the substrate of FIG. 8 at a processing step subsequent to that shown in FIG. 8;

[0022] FIG. 10 shows the substrate of FIG. 9 at a processing step subsequent to that shown in FIG. 9;

[0023] FIG. 11 shows the substrate of FIG. 10 at a processing step subsequent to that shown in FIG. 10;

[0024] FIG. 11A shows an alternative embodiment of the substrate shown in FIG. 11;

[0025] FIG. 12 is a flowchart showing the steps of fabricating a memory element in accordance with a second preferred embodiment of the present invention;

[0026] FIG. 13 shows the substrate of FIG. 10 undergoing the process of the second preferred embodiment of the present invention;

[0027] FIG. 14 shows the substrate of FIG. 13 at a processing step subsequent to that shown in FIG. 13;

[0028] FIG. 15 shows the substrate of FIG. 14 at a processing step subsequent to that shown in FIG. 14;

[0029] FIG. 16 shows the substrate of FIG. 15 at a processing step subsequent to that shown in FIG. 15;

[0030] FIG. 16A shows an alternative embodiment of the substrate shown in FIG. 16;

[0031] FIG. 17 shows an additional memory element according to second preferred embodiment of the present invention;

[0032] FIG. 17A shows an alternative embodiment of the substrate shown in FIG. 17.

DETAILED DESCRIPTION

[0033] In the following description, reference is made to the accompanying drawings which will serve to illustrate exemplary embodiments of the invention. The description provides sufficient detail to enable those skilled in the art to practice the invention. Of course other embodiments may be used and various changes may be

made without departing from the scope of the present invention. The scope of this invention is defined by the appended claims.

[0034] The term “substrate” used in the following description may include any supporting structure including, but not limited to, a plastic or a semiconductor substrate that has an exposed substrate surface. Semiconductor substrates should be understood to include silicon, silicon-on-insulator (SOI), silicon-on-sapphire (SOS), doped and undoped semiconductors, epitaxial layers of silicon supported by a base semiconductor foundation, and other semiconductor structures. When reference is made to a semiconductor substrate or wafer in the following description, previous process steps may have been utilized to form regions or junctions in or over the base semiconductor or foundation.

[0035] The term “silver” is intended to include not only elemental silver, but silver with other trace metals or in various alloyed combinations with other metals as known in the semiconductor industry, as long as such silver alloy is conductive, and as long as the physical and electrical properties of the silver remain unchanged.

[0036] The term “silver-selenide” is intended to include various species of silver-selenide, including some species which have a slight excess or deficit of silver, for instance, Ag_2Se , Ag_{2+x}Se , and Ag_{2-x}Se .

[0037] The term “semi-volatile memory device” is intended to include any memory device which is capable of maintaining its memory state after power is removed from the device for a prolonged period of time. Thus, semi-volatile memory devices are

capable of retaining stored data after the power source is disconnected or removed.

The term "semi-volatile memory device" as used herein includes not only semi-volatile memory devices, but also non-volatile memory devices.

[0038] FIG. 3 shows a memory element 50 at a stage of the fabrication process known in the art. A first insulating layer 54 has been formed on a substrate 52, which can be made of a material such as a silicon substrate or a variety of other materials such as plastic. Insulating layer 54 may be formed by any known deposition method, such as sputtering by chemical vapor deposition (CVD), plasma enhanced CVD (PECVS), or physical vapor deposition (PVD). First insulating layer 54 may be formed of a conventional insulating oxide, such as silicon oxide (SiO_2), silicon nitride (Si_3N_4), or any other low dielectric constant material. FIG. 3 further provides a bottom electrode 56 formed over first insulating layer 54. The bottom electrode 56 preferably comprises tungsten, but may comprise any conductive material.

[0039] Using the FIG. 3 structure containing bottom electrode 56 as a starting point and referring to the processing sequence shown in FIG. 2, a first embodiment of the invention will now be explained. At step 300 in FIG. 2, a second insulating layer 58 is formed over bottom electrode 56, as shown in FIG. 3. The second insulating layer 58 may comprise the same materials as first insulating layer 54, such as SiO_2 and Si_3N_4 . At step 310 an opening 60 is formed in second insulating layer 58 to provide the structure shown in FIG. 4. Opening 60 may be formed by known methods in the art, such as a conventional patterning and etching process. Opening 60 is formed such that the surface of bottom electrode 56 is exposed in opening 60. After the patterning and

etch back process any masking material used is stripped away to leave the structure at a state represented in FIG. 4.

[0040] At step 320 a first chalcogenide glass, preferably a germanium-selenide glass layer 62, is formed in opening 60 on top of bottom electrode 58. The first germanium-selenide glass layer 62 is preferably germanium-selenide of Ge_xSe_{100-x} stoichiometry. More preferably germanium-selenide glass layer 62 has formula Ge_xSe_{100-x} where x is between about 18 and about 33 or about 38 and about 43.

[0041] The formation of the first germanium-selenide glass layer 62 having the preferred stoichiometric formula may be accomplished by any appropriate method. Evaporation, co-sputtering germanium and selenium in appropriate ratios, sputtering using a germanium-selenide target having the desired stoichiometry, or chemical vapor deposition with stoichiometric amounts of GeH_4 and SeH_2 gases (or various compositions of these gases), which result in a germanium-selenide layer of the desired stoichiometry are methods which may be used to form germanium-selenide glass layer 62. First germanium-selenide glass layer 62 is then planarized and etched back by techniques known in the art to provide a structure such as a that shown in FIG. 5.

[0042] Referring back to FIG. 2, a metal, preferably silver, is incorporated into the first germanium-selenide glass layer 62 at step 330. Preferably, about 1% to about 10% less than the maximum amount of silver necessary to keep first germanium-selenide glass layer 62 in an amorphous state is ultimately incorporated into the glass layer, totaling less than or equal to about 33% of the glass layer. The method by which the

metal is incorporated into the first germanium-selenide glass layer 62 depends on the stoichiometry of the germanium-selenide glass. For example, when a germanium-selenide glass layer having a stoichiometry of Ge_xSe_{100-x} , the value of x determines the method by which metal is incorporated into the germanium-selenide glass layer. For germanium-selenide glass of formula Ge_xSe_{100-x} , where x is less than or equal to 33, for example, metal may be introduced into first germanium-selenide glass layer 62 by treatment with light irradiation.

[0043] Specifically, referring now to FIG. 6, a metal-containing layer 64 (preferably containing silver (Ag) or silver-selenide) is deposited over first germanium-selenide glass layer 62. For purposes of simplified discussion, metal and metal-containing layer 64 will be further described herein as silver and a silver-containing layer.

[0044] The method of incorporating silver into germanium-selenide glass layer 62 varies according to the silver-containing layer 64 utilized. Where silver-containing layer 64 is silver, for example, incorporation of silver into the first germanium-selenide glass layer 62 may be accomplished by irradiating the layers with light. The layers are irradiated for about 5 to 30 minutes at between about 1 mW/cm² to about 10 mW/cm² with electromagnetic radiation from a wavelength of about 200 nm to about 600 nm. The irradiation process breaks Ge-Se and Se-Se bonds in the first germanium-selenide glass layer 62, allowing Se from germanium-selenide layer 62 to combine with Ag provided in silver-containing layer 64 and forming silver-selenide first germanium-selenide glass layer 62. In addition, irradiation may be used in combination with a

thermal process using a temperature of about 50° C to about 350° C, and preferably about 110° C for about 5 to about 15 minutes, and more preferably about 10 minutes. This heating drives silver from silver-containing layer 64 into first germanium-selenide glass layer 62, which may provide an additional source of Ag to bond with Se after the light treatment. Removing excess silver-containing layer 64 from device 50 leaves a first silver-containing germanium-selenide glass layer 68, as shown in FIG. 7. Other embodiments of the present invention may retain silver-containing layer 64.

[0045] Referring back to FIG. 6, if silver-containing layer 64 is silver-selenide, first silver-containing germanium-selenide layer 68 may alternatively be obtained by virtue of adjacent placement of germanium-selenide glass layer 62 and silver-containing layer 64 without the irradiation step described above.

[0046] For embodiments of the present invention utilizing a first germanium-selenide glass layer 62 with Ge_xSe_{100-x} stoichiometry and x between about 38 and about 43, silver may be introduced to the germanium-selenide glass layer by utilizing a silver-selenide layer as described above. Specifically, referring now to FIG. 6A, a metal-chalcogenide layer 66 is deposited on first germanium-selenide glass layer 62. Preferably the metal chalcogenide includes silver-selenide. For the purposes of simplified discussion, the metal chalcogenide layer 66 will be further described herein as a silver-selenide layer. Silver-selenide layer 66 may be deposited by any suitable method known in the art, with dry plasma deposition (DPD) preferred. Silver-selenide migrates into first germanium-selenide glass layer 62. Referring to FIG. 7A, this migration of silver into the germanium-selenide glass changes the composition of the first

germanium-selenide glass layer to that of a first silver-containing germanium-selenide glass layer 68. Silver-selenide layer 66 may then be removed by any method known in the art.

[0047] Regardless of which method is employed to incorporate silver into first germanium-selenide glass layer 62 to form a first silver-containing germanium-selenide glass layer 68, a second silver-containing germanium-selenide glass layer is subsequently formed in the present invention. Referring to FIG. 2, at step 340 a second chalcogenide glass, preferably a second germanium-selenide glass layer 70, is deposited in opening 60, as shown in FIG. 8. This may be accomplished in the same ways that first germanium-selenide glass layer 62 is deposited at step 320. This second germanium-selenide glass layer 70 preferably has a stoichiometry of Ge_xSe_{100-x} . The second germanium-selenide glass layer 70 preferably has more of an open glass matrix than the first germanium-selenide glass layer 62, i.e., the second germanium-selenide glass layer preferably contains a smaller proportion of germanium as demonstrated by a smaller value of x.

[0048] One preferred embodiment includes a first germanium-selenide glass layer 62 having a value of x of about 38 to about 43 (preferably with a value of x of about 40), and a second germanium-selenide glass layer 70 having a value of x of about 18 to about 33 with a value of about 25 preferable. This particular embodiment utilizes a first glass with a tight matrix and a second glass with an open matrix as defined by the value of x. It must be understood, however, that both glass can have open matrices and both can have tight matrices. In addition, a first germanium-selenide glass layer 62 may

be utilized that has a more open matrix than second germanium-selenide glass layer 70. The present invention requires only that there be a diversity in the value of x between the first and second germanium-selenide glass layers 62, 70. As with first germanium-selenide glass layer 62, the stoichiometry of second germanium-selenide glass layer 70 and its relative stoichiometry and glass matrix structure with respect to first germanium-selenide glass layer 62 is wholly dependent on the desired electrical character of the PCRAM element.

[0049] At step 350 of FIG. 2 silver is introduced into the second germanium-selenide glass layer 70. This may be carried out in accordance with the description of step 330 where silver is introduced into the first germanium-selenide glass layer 62. Referring to FIG. 8 and FIG. 9, where a second silver-containing layer 72 is silver, for example, incorporation of silver into the second germanium-selenide glass layer 70 may be accomplished by irradiating the layers with light, as described above. The thermal process described above may also be used with the irradiation process. Removing excess silver-containing layer 72 from device 50 leaves a second silver-containing germanium-selenide glass layer 74, as shown in FIG. 10. Other embodiments of the present invention may retain silver-containing layer 72.

[0050] Referring back to FIG. 9, if second silver-containing layer 72 is silver-selenide, second silver-containing germanium-selenide layer 74 may alternatively be obtained by virtue of adjacent placement of germanium-selenide glass layer 62 and silver-containing layer 64 without the irradiation step described above. Where x has a value between about 38 and 43, a silver-containing layer (preferably comprising silver-

selenide) is deposited over second germanium-selenide glass layer 70, and silver is allowed to migrate from the silver-containing layer to the second germanium-selenide glass layer 70, as in step 330.

[0051] Either method of incorporating silver into the germanium-selenide glass layer results in a second silver-containing germanium-selenide glass layer 74, as shown in FIG. 10 (where silver-containing layer 72 has been stripped). At step 360, an upper electrode is deposited over the previous layer to form a semiconductor device 50 as shown in FIG. 11. The upper electrode is preferably silver, but may comprise any suitable conductive material.

[0052] It should be recognized that the present invention may be utilized in any of a number of memory cell configurations known in the art. For example, the memory cell 50A shown in FIG. 11A is provided where bottom electrode 56 is deposited in an opening formed in first insulating layer 54, rather than on top of first insulating layer 54, as shown in FIG. 11. The specific memory cell configuration will vary according to the specific application of the desired memory cell by altering, among other factors, the deposition and etching processes employed.

[0053] Referring now to FIG. 12, a second embodiment of the present invention includes forming at least one additional silver-containing germanium-selenide glass layer above second silver-containing germanium-selenide glass layer 74. This is accomplished in the same way that second silver-containing germanium-selenide glass layer 74 is formed over first silver-containing germanium-selenide glass layer 68. Specifically, at

step 350A, a chalcogenide glass, preferably an additional germanium-selenide glass layer 80, is deposited in opening 60 as shown in FIG. 13. This may be accomplished in the same ways that second germanium-selenide glass layer 70 is deposited at step 340. The additional germanium-selenide glass layer 80 preferably has a stoichiometry of Ge_xSe_{100-x} . The additional germanium-selenide glass layer 80 has a glass matrix structure distinct from any adjacently placed germanium-selenide glass layer, including second silver-containing germanium-selenide glass layer 74 in the case of a first additional silver-containing germanium-selenide glass layer. The additional germanium-selenide glass layer 80 may have the same glass matrix structure as any germanium-selenide glass layer not adjacent to additional germanium-selenide glass layer 80, such as first silver-containing germanium-selenide glass layer 68.

[0054] At step 350B of FIG. 12, silver is introduced into the additional germanium-selenide glass layer 80. This may be carried out in accordance with the description of step 330 where silver is introduced into the first germanium-selenide glass layer 62. Referring to FIG. 8 and FIG. 9, where an additional silver-containing layer 82 is silver, for example, incorporation of silver into the additional germanium-selenide glass layer 80 may be accomplished by irradiating the layers with light, as described above. The thermal process described above may also be used with the irradiation process. Removing excess silver-containing layer 82 from device 50 leaves an additional silver-containing germanium-selenide glass layer 84, as shown in FIG. 15. Other embodiments of the present invention may retain silver-containing layer 82.

[0055] Referring back to FIG. 14, if additional silver-containing layer 82 is silver-selenide, additional silver-containing germanium-selenide layer 84 may alternatively be obtained by virtue of adjacent placement of additional germanium-selenide glass layer 80 and additional silver-containing layer 82 without the irradiation step described above. Where x has a value between about 38 and 43, a silver-containing layer (preferably comprising silver-selenide) is deposited over additional germanium-selenide glass layer 80, and silver is allowed to migrate from the silver-containing layer to the additional germanium-selenide glass layer 80, as in step 330. Either method of incorporating silver into the germanium-selenide glass layer results in an additional silver-containing germanium-selenide glass layer 84, as shown in FIG. 15 (where silver-containing layer 82 has been stripped).

[0056] At step 360, an upper electrode 76 is deposited over the previous layer (in this case 84) to form a semiconductor device 50 as shown in FIG. 16. The upper electrode is preferably silver, but may comprise any suitable conductive material.

[0057] Referring to FIG. 16, one preferred embodiment of the memory element comprising at least one additional germanium-selenide layer includes a first silver-containing germanium-selenide glass layer 68 having a value of x of about 38 to about 43 (preferably with a value of x of about 40), and a second silver-containing germanium-selenide glass layer 74 having a value of x of about 18 to about 33 with a value of about 25 preferable. The at least one additional silver-containing germanium-selenide layer 84 has a value of x different from the value of x for the second silver-containing germanium-selenide glass layer 74, and preferably from about 38 to about

43, more preferably 40, the same value as x for the first silver-containing germanium-selenide glass layer 68.

[0058] In the resulting memory element, first silver-containing germanium-selenide glass layer 68 and additional silver-containing germanium-selenide glass layer 84 have equal stoichiometries providing a tight glass matrix structure, while second silver-containing germanium-selenide glass layer 74 has a stoichiometry providing an open glass matrix structure. However, as discussed above with reference to the first embodiment of the present invention, and FIG. 5 and FIG. 8, first and second germanium-selenide glass layers 62, 70 (and consequently first and second silver-containing germanium-selenide layers 68, 74) need only have diverse values of x, without a requirement that the first germanium-selenide glass layer 62 have a higher value of x or a tighter glass matrix structure than second germanium-selenide glass layer 70. The present invention likewise does not require that additional germanium-selenide glass layer 80 (and consequently additional silver-containing germanium-selenide glass layer 84) have any particular value of x or glass matrix structure. Additional silver-containing germanium-selenide glass layer 84 must only have a value of x and a glass matrix structure different from adjacent silver-containing germanium-selenide glass layers, such as the second silver-containing germanium-selenide glass layer 74.

[0059] As with FIG. 11A, the memory cell 50A shown in FIG. 16A is provided where bottom electrode 56 is deposited in an opening formed in first insulating layer 54, rather than on top of first insulating layer 54, as shown in FIG. 16. The specific memory cell configuration will vary according to the specific application of the desired

memory cell by altering, among other factors, the deposition and etching processes employed.

[0060] Referring to FIG. 16, this allows for many embodiments provided by the present invention. For example, in addition to the previously disclosed embodiment where first and additional silver-containing germanium-selenide glass layers 68, 84 had equal values of x providing tighter glass matrix structures and second silver-containing germanium-selenide glass layer 74 had a more open glass structure, first and additional silver-containing germanium-selenide glass layers 68, 84 may have equal values of x providing more open glass matrix structure compared to second silver-containing germanium-selenide glass layer 74 having a more tight glass matrix structure. Furthermore, first silver-containing germanium-selenide glass layer 68 may have a more tight glass matrix structure than second silver-containing germanium-selenide glass layer 74, which in turn may have a more tight glass matrix structure than additional silver-containing germanium-selenide glass layer 84, providing a stack of silver-containing germanium-selenide glass layers with descendingly graded stoichiometries. These values of x can be inverted to provide a stack of silver-containing germanium-selenide glass layers with ascendingly graded stoichiometries.

[0061] It should be readily apparent to a person of ordinary skill in the art that the present invention provides many combinations of silver-containing germanium-selenide stacks for use in memory fabrication. Referring now to FIG. 17, it is clear that a memory element fabricated according to the present invention also is not limited in the number of silver-containing germanium-selenide layers included. FIG. 17 provides

four distinct silver-containing germanium-selenide glass layers 68, 74, 84, and 86. Stoichiometries which may be used are those included in the above description of forming memory elements comprising at least one additional silver-containing germanium-selenide glass layer. As with FIG. 11A and FIG. 16A above, memory cell 50A shown in FIG. 17A is provided where bottom electrode 56 is deposited in an opening formed in first insulating layer 54, rather than on top of first insulating layer 54, as shown in FIG. 17. The specific memory cell configuration will vary according to the specific application of the desired memory cell by altering, among other factors, the deposition and etching processes employed.

[0062] The combination of silver-containing germanium-selenide glass layers 68, 74 (and 84, 86 in embodiments comprising at least one additional silver-containing germanium-selenide glass layer) may be selected according to the desired electronic characteristics of the memory element being fabricated. Additionally, utilizing a relatively open-matrix germanium-selenide glass layers with tighter-matrix rigid glass layers provides increased adhesion between the glass and the semiconductor side walls. This is because a more open-matrix glass has greater ability to deform to surface defects and therefore provides greater surface area for contact. The increased presence of free selenium in open-matrix glass may also form bonds with side wall constituents such as silicon, thus aiding in adhesion.

[0063] PCRAM performance with respect to both electrical characteristics and side wall adhesion will vary depending on the germanium-selenide glass composition, the order of silver-containing germanium-selenide glass layers, and the number of silver-

containing germanium-selenide glass layers. It should therefore be readily understood that the invention can be modified in these specific respects as well as to any number of variations, alterations, substitutions or equivalent arrangements not heretofore described, but which are commensurate with the spirit and scope of the invention in order to obtain a desired memory functionality. Accordingly, the invention is not to be seen as limited by the foregoing description, but is only limited by the scope of the appended claims.